



Material Content Data Sheet



Sales Product Name		TLE7259-3GE		Issued		28. August 2013		
MA#		MA001102856						
Package		PG-DSO-8-16		Weight*		83.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.228	2.67	2.67	26744	26744
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8611	
wire	non noble metal	copper	7440-50-8	29.121	34.96	35.87	349625	358775
	noble metal	gold	7440-57-5	0.193	0.23	0.23	2323	2323
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1160
plastics	plastics	epoxy resin	-	4.443	5.33		53344	
	inorganic material	silicondioxide	60676-86-0	43.755	52.55	58.00	525319	579823
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9771	9771
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7807	7807
glue	plastics	acrylic resin	-	0.270	0.32		3247	
	noble metal	silver	7440-22-4	0.959	1.15	1.47	11510	14757
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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